

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	"6548121", PN	USPAT; USOCR	OR	OFF	2009/02/19 16:58
S2	1180	"cba specialty chemicals corporation" as:	US-PPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:03
S3	5	"cba specialty chemicals corporation" as: and strongly adherent coatings	US-PPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S4	5	"cba specialty chemicals corporation" as: and strongly adherent coating	US-PPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S5	1	10/566743 app.	US-PPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:37
S6	1	("7455891", PN	USPAT; USOCR	OR	OFF	2009/02/20 11:00
S7	8	((7455891) or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362")), PN	USPAT; USOCR	OR	OFF	2009/02/20 11:09
S8	9	((7455891) or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362") or ("6399805")), PN	USPAT; USOCR	OR	OFF	2009/02/20 11:14
S9	108	"369951" "363509" "4082679" "4199421" "4226763" "4246315" "4275004" "4278589" "429152" "4298738" "4315848" "4324744" "4347180" "4385109" "4466993" "4533652" "4567106" "4681905" "4684679" "4684680" "4710523" "4737593" "4792632" "4861616" "486246" "4962594" "4990364" "505246" "5080994" "510681" "5108835" "5116534" "5153284" "5166355" "5168087" "5196142" "5218009" "5260698" "5252403" "5276314" "5280124" "5292690" "5330539" "5360650" "5399770" "5436349" "5456728" "5472992" "5504236" "5516914" "5549847" "5554760" "5563242" "5574166" "5607987" "5646088" "5935900" "5942290" "5955514" "599169" "6099122" "6190423" "6329445" "6344505" "6361925" "6376065" "6399805" "6407254" "6548121" "6733847"), PN OR ("6251963" "6368362" "6399805" "6486228" "6515051" "6548121" "6733847" "6803392" "7455891"), UPRN	US-PPUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:21
S10	15	((4199421" "4246315" "4466993" "4567106" "4990364" "5053246" "5252403" "6099122" "6548121" "6733847"), PN OR ("6548121" "6733847" "7455891"), UPRN	US-PPUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:22
S11	21168	427/533.535.538.517.407.1-412.5.532.559.517.509.512.513.517.518.519.520.535.536.538.551.553.554.556.407.2.409.412.412.1.419.2.cds. or 430/311.cds.	US-PPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27

S12	5299	427/533,509 cts. or 430/311 cts.	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S13	211	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metalized with (organic or polymer) with substrate	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S14	139	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metalized with (organic or polymer) with substrate and @PY<*2004*	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S15	13	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metalized with (organic or polymer) with substrate and @PY<*2004* and S11	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S16	7	circuit and photoinitiator with adhesion with metal	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 16:56
S17	183	circuit and photoinitiator with adhesion and (metal or copper)	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S18	13	circuit and photoinitiator with adhesion with (metal or copper)	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S19	613	circuit and photoresist with adhesion with (metal or copper)	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S20	283	circuit and photoresist with adhesion with (metal or copper) and plasma	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S21	47	circuit and photoresist with adhesion with (metal or copper) with plasma	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:19
S22	10	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion with (metal or copper) with plasma	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34

S23	10	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) and adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S24	1116	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S25	146	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S26	10	solder mask with UV with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:40
S27	2	"20030129322" dd.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:42
S28	13	solder mask with (cvd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:38
S29	692	solder with (cvd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:41
S30	5	solder with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:43
S31	149	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S32	12645	metal with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S33	45	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @?<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44

S34	580	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S35	25	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S36	3	wiring board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:58
S37	21	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004" and cmp	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 19:05
S38	1	(*6524950*), PN	USPAT; USCOOP	OR	OFF	2009/02/20 19:21
S39	600	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S40	189	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and @PY<"2003"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S41	12	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:25
S42	10	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S43	10	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2004"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S44	73	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 and @PY<"2004"	US-PPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34

S45	1721	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or meta\$3 or glass or metal oxide) with substrate and @PY<"2004"	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:42
S46	132	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or meta\$3 or glass or metal oxide) with substrate and (sputter or evaporate) with (metal or half-metal) and @PY<"2004"	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:43
S47	265	427/98.5.oids.	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:01
S48	95	427/98.5.oids. and (resist or photoinitiator)	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:02
S49	26	427/98.5.oids. and (resist or photoinitiator) and plasma	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:03
S50	2	10/502208.app.	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 15:36
S51	1	trimethylbenzyl allyl phenyl phosphine oxide	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/24 13:17
S52	12	["2002026049" "20050147919" "6399805" "6548121" "6589550" "6733847"] PN.	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/25 12:09
S53	2	{09/871373 10/502208}.APP.	USPAT; USOCR	ADJ	ON	2009/02/25 12:10
S54	11	wo-0024527-\$.oid.	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/25 14:05
S55	0	EP-0475592-\$.dd.	US-CPUB; USPAT; PPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27

S56	0	EP-0475592.dd	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27
S57	0	EP0475592.dd	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27
S58	2	"US 20060257681"	US-PO/PUB; USPAT; USCOOR; DERWENT	ADJ	ON	2010/03/24 14:32
S59	22	radiation with curing with dosage with crosslinking	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 15:58
S60	98	primer with photoinitiator with (irradiat\$3 or cur\$3 or crosslink\$3)	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 11:44
S61	2	jp-2001083301-\$.dd	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 12:23
S62	1	2001-338377.NPAN.	DERWENT	ADJ	ON	2010/04/01 12:24
S63	1	2001-338377.NPAN.	DERWENT	ADJ	ON	2010/04/01 12:24
S64	150	427/492.cds	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:08
S65	655	427/487.cds	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:24
S66	1148	427/508.cds	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27
S67	775	427/510.cds	US-PO/PUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27

S83	748	427/517-519.cds.	US-PGPUB, USPAT; FPRS, EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/04/01 17:27
S89	115	427/517-519.cds. and primer	US-PGPUB, USPAT; FPRS, EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2010/04/01 17:27
S70	1	(*4,634,602*), PN	USPAT; USCOR	OR	OFF	2010/04/02 08:51
S71	31	(*3876432* *3899611* *4025407* *4128600* *4169732* *4205018* *4295947* *4342793* *4374963* *4391855* *4425207*), PN, OR (*4634602*), UPRN	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 09:01
S77	15	(*2873241* *3088791* *3131138* *3453195*), PN, OR (*4778724*), UPRN	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 10:34
S78	15	(*2873241* *3088791* *3131138* *3453195*), PN, OR (*3892885*), UPRN	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 11:25
S79	23	(*3661614* *4188451* *4190631* *4197335* *4198465* *4218294* *4222835* *4264658* *4384026* *4396578*), PN, OR (*4902578*), UPRN	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 15:51
S81	0	DE-19953433-\$, did.	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 16:55
S82	0	DE-1995003433-\$, did.	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 16:56
S83	0	DE-95003433-\$, did.	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 16:56
S84	0	DE-953433-\$, did.	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 16:56
S85	1611	427/508-510.cds.	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 17:00
S86	204	427/508-510.cds. and metal\$4 and primer	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 17:01
S87	148	427/508-510.cds. and metal\$4 with (coating or layer or film) and primer	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/02 17:01
S88	7	427/508-510.cds. and metal\$4 with (coating or layer or film) and primer with (\$5initiator) with (cur\$3 or crosslink\$3)	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 15:48
S89	8	427/508-510.cds. and metal\$4 and primer with (\$5initiator) with (cur\$3 or crosslink\$3)	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 15:51
S90	185	427/508-510.cds. and metal\$4 with substrate and (\$5initiator) with (cur\$3 or crosslink\$3)	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 15:51
S91	0	427/508-510.cds. and metal\$4 with substrate and (multicoat\$3 or multilayer) and (\$5initiator) with cur\$3 with uncur\$3	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 16:41
S92	2	427/508-510.cds. and (multicoat\$3 or multilayer) and (\$5initiator) with cur\$3 with uncur\$3	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 16:41
S93	2	427/508-510.cds. and (multicoat\$3 or multilayer) and (\$5initiator) with cur\$3 with (stable)	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 16:42
S94	57	427/508-510.cds. and (multicoat\$3 or multilayer) and photoinitiator with cur\$3	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 16:42
S95	49	427/508-510.cds. and (multicoat\$3 or multilayer) and photoinitiator with cur\$3 and metal\$4	US-PGPUB, USPAT; USCOR	ADJ	ON	2010/04/05 16:43

S96	10	427/508-510.cds. and (multicoat\$3 or multilayer) and photoinitiator with partia\$2 cur\$3	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S97	2	427/508-510.cds. and photoinitiator with partial\$2 cur\$3	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S98	4	427/508-510.cds. and photoinitiator with partial\$2 near5 cur\$3	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S99	5	427/508-510.cds. and partial\$2 near5 cur\$3 with unsaturated	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
S100	195	427/508-510.cds. and partial\$2 near5 cur\$3	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
S101	109	427/508-510.cds. and partial\$2 near5 cur\$3 and photoinitiator	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
S102	151	427/508-510.cds. and partial\$2 near5 cur\$3 and metal\$3	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
S103	148	427/508-510.cds. and metal\$4 with (coating or layer or film) and primer	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S104	126	427/508-510.cds. and partial\$2 near5 cur\$3 and metal\$3 not S103	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S105	22	427/508-510.cds. and partial\$2 near5 cur\$3 and metal\$3 not S103 and multilayer	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S106	23	427/508-510.cds. and partial\$2 near5 cur\$3 and metal\$3 not S103 and multilayer\$3	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
S107	1	wo-0232201-\$.cd	US-CPUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:32
S108	2	jp-2001217529-\$.cd	US-CPUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:42
S109	2	jp-2001046940-\$.cd	US-CPUB; USPAT; FFPS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:46
S110	1	2001-567393.NRAN	DERWENT	ADJ	ON	2010/04/07 09:48
S111	5	427/508-510.cds. and metal\$3 with (evaporat\$3 or sputter\$3) and multilayer\$3 and ("UVVIS" or UV or ultraviolet) with cur\$4 and photoinitiator and acrylates	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/07 13:57
S112	1	20040011289-.pn	US-CPUB; USPAT; USOCR	ADJ	ON	2010/04/07 17:13

EAST Search History (Interference)

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